

### FEATURES:

- No cross talk between inductors due to magnetic shielding
- Size range: 0603 and 0805
- Inductance range: 0.01uH to 22uH
- Rated current: 5mA to 50mA
- Unified automatic mounting shape with no directionality
- Ferrite core



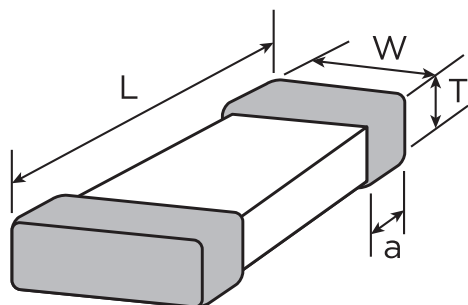
### PART NUMBER STRUCTURE

MLF	1608	-	47N	M	T
Series	Size		Inductance Value	Tolerance	Packaging
	1608 2012		47N = .047uH R39 = .39uH 8R2 = 8.2uH	K = ±10% M = ±20%	T = Tape & Reel

Example P/N: MLF1608-47NMT

Standard Termination is 100% matte Tin over Nickel.

### DIMENSIONS



Unit: mm (inches)

SIZE	L	W	T	a
<b>1608</b> (0603)	1.6 ± 0.15 (0.064 ± .006)	0.8 ± 0.15 (0.032 ± .006)	0.8 ± 0.15 (0.032 ± .006) 1.2 ± 0.2 (0.048 ± .008)	0.3 ± 0.2 (0.012 ± .008)
<b>2012</b> (0805)	2.0 ± 0.2 (0.080 ± .008)	1.25 ± 0.2 (0.050 ± .008)	0.85 ± 0.2 (0.034 ± .008) 1.25 ± 0.2 (0.050 ± .008)	0.3 ± 0.2 (0.012 ± 0.008)

### OPERATING / STORAGE TEMPERATURE RANGE

Operating Temperature Range	-40 to +85° C
Storage Temperature Range	-10 to +40° C

**ELECTRICAL SPECIFICATION & RANGE**

**1608 (0603)**

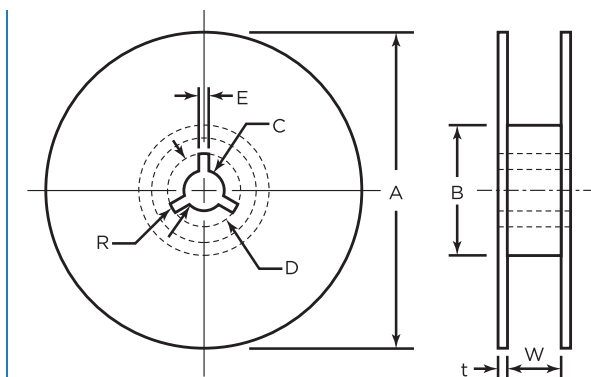
INDUCTANCE (uH)	TOLERANCE (%)	L/Q FREQ. (MHz)	Q MIN.	SELF-RESONANT FREQUENCY (MHz)	DC RESISTANCE (Ω)	RATED CURRENT (mA)	VENKEL PART NUMBER
0.01	±20%	50	10	300	0.20	50	MLF1608-10NMT
0.033	±20%	50	10	270	0.20	50	MLF1608-33NMT
0.047	±20%	50	10	260	0.30	50	MLF1608-47NMT
0.056	±20%	50	10	255	0.30	50	MLF1608-56NMT
0.068	±20%	50	10	250	0.30	50	MLF1608-68NMT
0.082	±20%	50	10	245	0.30	50	MLF1608-82NMT
0.1	±10%, ±20%	50	15	240	0.50	50	MLF1608-R10CT
0.12	±10%, ±20%	25	15	205	0.50	50	MLF1608-R12CT
0.15	±10%, ±20%	25	15	180	0.60	50	MLF1608-R15CT
0.18	±10%, ±20%	25	15	165	0.60	50	MLF1608-R18CT
0.22	±10%, ±20%	25	15	150	0.80	50	MLF1608-R22CT
0.27	±10%, ±20%	25	15	136	0.80	50	MLF1608-R27CT
0.33	±10%, ±20%	25	15	125	0.85	35	MLF1608-R33CT
0.39	±10%, ±20%	25	15	110	1.00	35	MLF1608-R39CT
0.47	±10%, ±20%	25	15	105	1.35	35	MLF1608-R47CT
0.56	±10%, ±20%	25	15	95	1.55	35	MLF1608-R56CT
0.68	±10%, ±20%	25	15	85	1.70	35	MLF1608-R68CT
0.82	±10%, ±20%	25	15	75	2.10	35	MLF1608-R82CT
1	±10%, ±20%	10	35	65	0.60	25	MLF1608-1R0CT
1.2	±10%, ±20%	10	35	60	0.80	25	MLF1608-1R2CT
1.5	±10%, ±20%	10	35	55	0.80	25	MLF1608-1R5CT
1.8	±10%, ±20%	10	35	50	0.95	25	MLF1608-1R8CT
2.2	±10%, ±20%	10	35	45	1.55	15	MLF1608-2R2CT
2.7	±10%, ±20%	10	35	40	1.35	15	MLF1608-2R7CT
3.3	±10%, ±20%	10	35	35	1.55	15	MLF1608-3R3CT
3.9	±10%, ±20%	10	35	35	1.70	15	MLF1608-3R9CT
4.7	±10%, ±20%	10	35	30	2.10	15	MLF1608-4R7CT
5.6	±10%, ±20%	4	35	20	1.55	5	MLF1608-5R6CT
6.8	±10%, ±20%	4	35	20	1.70	5	MLF1608-6R8CT
8.2	±10%, ±20%	4	30	15	2.10	5	MLF1608-8R2CT
10	±10%, ±20%	4	30	15	2.55	5	MLF1608-10CT

### ELECTRICAL SPECIFICATION & RANGE

#### 2012 (0805)

INDUCTANCE (uH)	TOLERANCE (%)	L/Q FREQ. (MHz)	Q MIN.	SELF-RESONANT FREQUENCY (MHz)	DC RESISTANCE (Ω)	RATED CURRENT (mA)	VENKEL PART NUMBER
0.047	±20%	50	20	320	0.20	300	MLF2012-47NMT
0.056	±20%	50	20	320	0.20	300	MLF2012-56NMT
0.068	±20%	50	20	280	0.20	300	MLF2012-68NMT
0.082	±20%	50	20	255	0.20	300	MLF2012-82NMT
0.1	±10%, ±20%	25	20	235	0.30	250	MLF2012-R10□T
0.12	±10%, ±20%	25	20	220	0.30	250	MLF2012-R12□T
0.15	±10%, ±20%	25	20	200	0.40	250	MLF2012-R15□T
0.18	±10%, ±20%	25	20	185	0.40	250	MLF2012-R18□T
0.22	±10%, ±20%	25	20	170	0.50	250	MLF2012-R22□T
0.27	±10%, ±20%	25	20	150	0.50	250	MLF2012-R27□T
0.33	±10%, ±20%	25	20	145	0.55	250	MLF2012-R33□T
0.39	±10%, ±20%	25	25	135	0.65	200	MLF2012-R39□T
0.47	±10%, ±20%	25	25	125	0.65	200	MLF2012-R47□T
0.56	±10%, ±20%	25	25	115	0.75	150	MLF2012-R56□T
0.68	±10%, ±20%	25	25	105	0.80	150	MLF2012-R68□T
0.82	±10%, ±20%	25	25	100	1.00	150	MLF2012-R82□T
1	±10%, ±20%	10	45	75	0.40	50	MLF2012-1R0□T
1.2	±10%, ±20%	10	45	65	0.50	50	MLF2012-1R2□T
1.5	±10%, ±20%	10	45	60	0.50	50	MLF2012-1R5□T
1.8	±10%, ±20%	10	45	55	0.60	50	MLF2012-1R8□T
2.2	±10%, ±20%	10	45	50	0.65	30	MLF2012-2R2□T
2.7	±10%, ±20%	10	45	45	0.75	30	MLF2012-2R7□T
3.3	±10%, ±20%	10	45	41	0.80	30	MLF2012-3R3□T
3.9	±10%, ±20%	10	45	38	0.90	30	MLF2012-3R9□T
4.7	±10%, ±20%	4	45	35	1.00	30	MLF2012-4R7□T
5.6	±10%, ±20%	4	45	32	0.90	15	MLF2012-5R6□T
6.8	±10%, ±20%	4	45	29	1.00	15	MLF2012-6R8□T
8.2	±10%, ±20%	4	45	26	1.10	15	MLF2012-8R2□T
10	±10%, ±20%	2	45	24	1.15	15	MLF2012-100□T
12	±10%, ±20%	2	45	22	1.25	15	MLF2012-120□T
15	±10%, ±20%	1	30	19	0.80	5	MLF2012-150□T
18	±10%, ±20%	1	30	18	0.90	5	MLF2012-180□T
22	±10%, ±20%	1	30	16	1.10	5	MLF2012-220□T

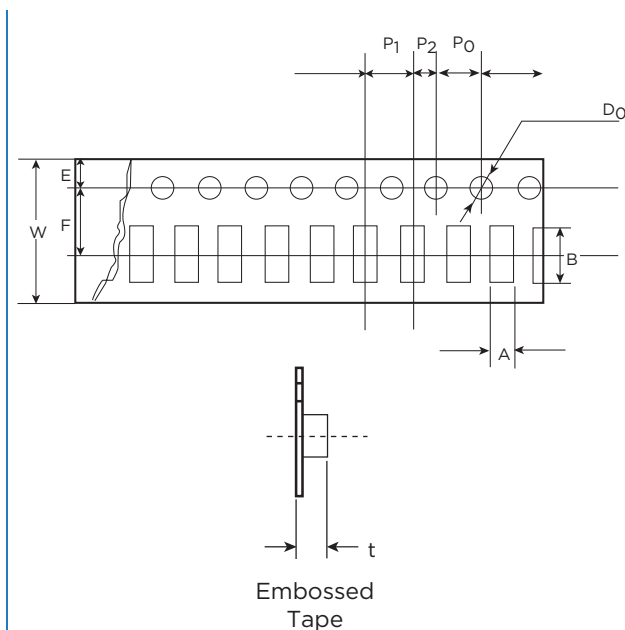
### REEL SPECIFICATIONS



Unit: mm

TAPE WIDTH	8mm	12mm
A	178 ± 2	178 ± 2
B	50 ± 1	50 ± 1
C	13.0 ± 0.5	13.0 ± 0.5
D	21.0 ± 0.8	21.0 ± 0.8
E	2.0 ± 0.5	2.0 ± 0.5
W	10.0 ± 1.0	14.0 ± 1.0
t	1.2 ± 0.5	2.0 ± 0.5
R	1.0	1.0

### TAPE SPECIFICATIONS



Units: mm

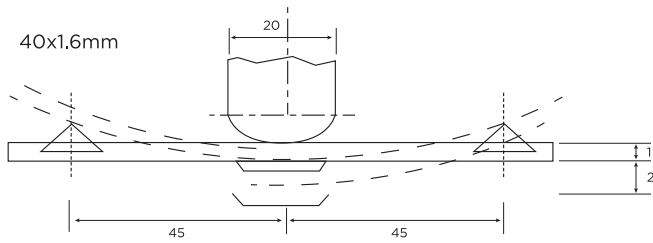
SIZE	0603 (1608)	0805 (2012) (≤ 2.2uH)	0805 (2012) (≥ 2.7uH)
Tape	Embossed	Embossed	Embossed
W	8.0 ± 0.2	8.0 ± 0.2	8.0 ± 0.2
F	3.5 ± 0.05	3.5 ± 0.05	3.5 ± 0.05
E	1.75 ± 0.1	1.75 ± 0.1	1.75 ± 0.1
P <sub>1</sub>	4.0 ± 0.1	4.0 ± 0.1	4.0 ± 0.1
P <sub>2</sub>	2.0 ± 0.05	2.0 ± 0.05	2.0 ± 0.05
P <sub>0</sub>	4.0 ± 0.1	4.0 ± 0.1	4.0 ± 0.1
D <sub>0</sub>	1.5 ± 0.1	1.5 ± 0.1	1.5 ± 0.1
A	1.40 ± 0.2	1.42 ± 0.1	1.42 ± 0.1
B	1.8 ± 0.20	2.26 ± 0.1	2.26 ± 0.1
t	1.15 ± 0.1	1.30 ± 0.1	1.30 ± 0.1
Qty/Reel	4,000	4,000	3,000

### ENVIRONMENTAL CHARACTERISTICS

#### ELECTRICAL PERFORMANCE TEST

TEST	REQUIREMENT	TEST METHOD
Inductance	Refer to standard electrical characteristic spec.	HP4291B
Q		HP4291B
SRF		HP4291B
DC Resistance RDC		Agilent 34401A
ID		The DC current value having temperature increased 40°C after thru DC current 2 hours at ambient temperature

#### MECHANICAL PERFORMANCE TEST

TEST	REQUIREMENT	TEST METHOD
Resistance to Soldering Heat	Appearance: No damage More than 75% of the terminal. Electrode should be covered with solder.	Pre-heating: 150°C, 1min. Solder Composition: Sn/Ag3.0/Cu0.5 (Pb-Free) Solder Temperature: 260±5°C (Pb-Free) Immersion Time: 10±1 sec.
Solderability	The electrodes shall be at least 90% covered with new solder coating	Pre-heating: 150°C, 1min. Solder Composition: Sn/Ag3.0/Cu0.5 (Pb-Free) Solder Temperature: 245±5°C (Pb-Free) Immersion Time: 4±1 sec.
Flexure Strength	The forces applied on the right conditions must not damage the terminal electrode and the ferrite.	<p>Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6 mm Deflection: 2.0 mm Keeping Time: 30 sec.</p>  <p>*For 0402, substrate dimension is 100x40x0.8 mm</p>
Vibration		Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1 min. Amplitude: 1.5 mm Time: 2 hrs for each axis (X, Y & Z), total 6 hrs

## Environmental Characteristics

### Climatic Test

Test	Requirement	Test Method															
Damp Heat with Load	Appearance: No damage L change: within±20% of initial value	Temperature: 40±2°C Relative Humidity: 90 ~ 95% Time: 1000 hrs Measured after exposure in the room condition for 24 hrs															
Temperature Cycle		One cycle: <table border="1" style="margin-left: 20px;"> <thead> <tr> <th>Step</th> <th>Temperature (°C)</th> <th>Time (min.)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-40±3</td> <td>30</td> </tr> <tr> <td>2</td> <td>25±2</td> <td>3</td> </tr> <tr> <td>3</td> <td>85±3</td> <td>30</td> </tr> <tr> <td>4</td> <td>25±2</td> <td>3</td> </tr> </tbody> </table> Total: 100 cycles Measured after exposure in the room condition for 24 hrs	Step	Temperature (°C)	Time (min.)	1	-40±3	30	2	25±2	3	3	85±3	30	4	25±2	3
Step		Temperature (°C)	Time (min.)														
1		-40±3	30														
2	25±2	3															
3	85±3	30															
4	25±2	3															
High Temperature Resistance	Temperature: 85±3°C Relative Humidity: 20% Applied Current: Rated Current Time: 1000 hrs Measured after exposure in the room condition for 24 hrs																
Low Temperature Resistance	Temperature: -40±3°C Relative Humidity: 0% Time: 1000 hrs Measured after exposure in the room condition for 24 hrs																

Storage Temperature: 15~28°C; Humidity < 80%RH